

50V Low Current Consumption 150mA CMOS Voltage Regulator

LR6675 Series

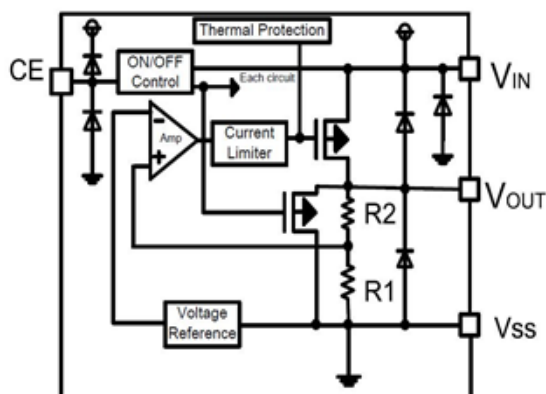
■ INTRODUCTION

The LR6675 series are a group of positive voltage regulators manufactured by CMOS technologies with low power consumption and low dropout voltage, which provide large output currents even when the difference of the input-output voltage is small. The LR6675 series can deliver 150mA output current and allow an input voltage as high as 60V. The series are very suitable for the battery-powered equipments, such as RF applications and other systems requiring a quiet voltage source.

■ APPLICATIONS

- Cordless Phones
- Radio control systems
- Laptop, Palmtops and PDAs
- Single-lens reflex DSC
- PC peripherals with memory

■ BLOCK DIAGRAM



■ FEATURES

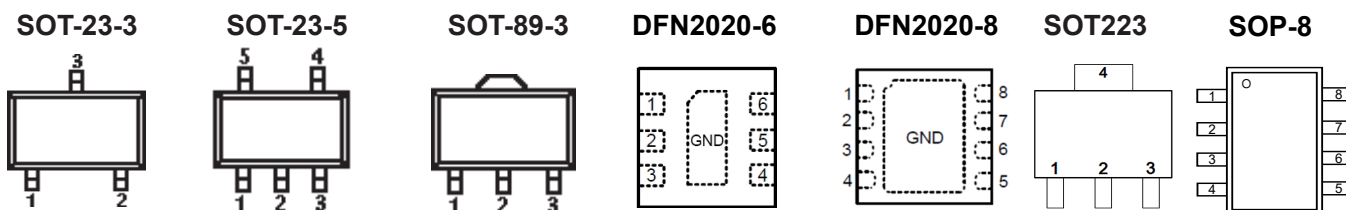
- Low Quiescent Current: 3μA
- Operating Voltage Range: 2.5V~50V
- Output Current: 150mA
- Low Dropout Voltage:
500mV@50mA(V_{OUT}=3.3V)
- Output Voltage: 1.2~12.0V
- High Accuracy: ±2%/±1% (Typ.)
- High Power Supply Rejection Ratio:
80dB@1kHz
- Low Output Noise:
27xV_{OUT} μV_{RMS} (10Hz~100kHz)
- Excellent Line and Load Transient Response
- Built-in Current Limiter, Short-Circuit Protection
- Over-Temperature Protection
- Wireless Communication Equipments
- Portable Audio Video Equipments
- Car Navigation Systems
- LAN Cards
- Ultra Low Power Microcontroller

■ ORDER INFORMATION

LR6675①②③④

DESIGNATOR	SYMBOL	DESCRIPTION
①	A	Without EN
	B	With Shutdown Function
②	Integer	Output Voltage e.g. 5.0V=50 12.0V=120
	M/MC/MY/MK	Package: SOT-23-3/5
③	P/PT/PL	Package: SOT-89-3
	FT	Package: DFN2020-6
	FL	Package: DFN2020-8
	S	Package: SOT223
	X	Package: SOP-8
④	-	2% Accuracy
	1	1% Accuracy

PIN CONFIGURATION



LR6675A

PIN NUMBER							PIN NAME	FUNCTION
SOT-23-3			SOT-89-3			SOT-223		
M	MC	MY	P	PT	PL	S		
1	3	3	1	2	2	2/4	V _{SS}	Ground
2	2	1	3	1	3	3	V _{OUT}	Output
3	1	2	2	3	1	1	V _{IN}	Power input

LR6675B

SOT-23-5

PIN NUMBER		SYMBOL	FUNCTION
M	MK		
1	1	V _{IN}	Power Input Pin
2	2	V _{SS}	Ground
3	4	CE	Chip Enable Pin
4	3	NC	No Connection
5	5	V _{OUT}	Output Pin

LR6675B

DFN2020-6/8

PIN NUMBER		PIN NAME	FUNCTION
FT	FL		
1	5/6	V _{IN}	Power input Pin
2	7	CE	Chip Enable Pin
3/4	8	V _{SS}	Ground
5	1/2	NC	Not Connection
6	3/4	V _{OUT}	Output Pin
EP	EP	Thermal Pad	Ground

LR6675B

SOP-8

PIN NUMBER		PIN NAME	FUNCTION
X			
1		V _{OUT}	Output Pin
2/5/6/7		NC	Not Connection
3		CE	Chip Enable Pin
4		V _{SS}	Ground
8		V _{IN}	Power input Pin

■ ABSOLUTE MAXIMUM RATINGS⁽¹⁾

(Unless otherwise specified, $T_A=25^{\circ}\text{C}$)

PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage ⁽²⁾		V_{IN}	-0.3~65	V
Output Voltage ⁽²⁾		V_{OUT}	-0.3~15	V
CE Pin Voltage ⁽²⁾		V_{CE}	-0.3~ $V_{IN}+0.3$	V
Output Current		I_{OUT}	400	mA
Power Dissipation	SOT-23	P_D	0.3	W
	SOT-89		0.5	W
Operating Junction Temperature Range		T_j	-40~125	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-40~125	$^{\circ}\text{C}$
Lead Temperature(Soldering, 10 sec)		T_{solder}	260	$^{\circ}\text{C}$
ESD rating ⁽³⁾	Human Body Model-(HBM)		2	kV
	Machine Model- (MM)		200	V

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network ground terminal.

(3) ESD testing is performed according to the respective AEC-Q100 standard.

The human body model is a 100 pF capacitor discharged through a 1.5k Ω resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin.

■ RECOMMENDED OPERATING CONDITIONS

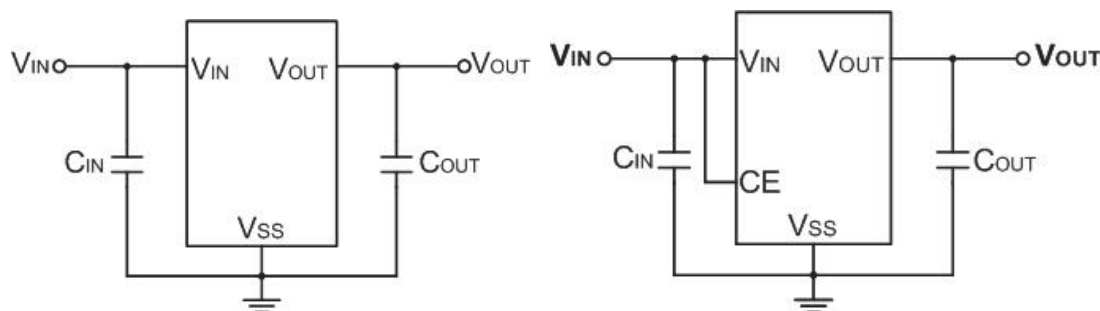
PARAMETER	MIN.	NOM.	MAX.	UNITS
Supply voltage at V_{IN}	2.5		50	V
Operating junction temperature range, T_j	-40		125	$^{\circ}\text{C}$
Operating free air temperature range, T_A	-40		85	$^{\circ}\text{C}$

■ ELECTRICAL CHARACTERISTICS

LR6675 Series ($V_{CE}=V_{IN}=V_{OUT}+2V$, $C_{IN}=C_{OUT}=1\mu F$, $T_A=25^\circ C$, unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP. ⁽⁴⁾	MAX.	UNITS
Input Voltage	V_{IN}		2.5	—	50	V
Output Voltage Range	V_{OUT}		1.2	—	12	V
DC Output Accuracy		$I_{OUT}=1mA$	-2	—	2	%
			-1	—	1	%
Dropout Voltage	$V_{dif}^{(5)}$	$I_{OUT}=50mA, V_{OUT}=3.3V$	—	500	—	mV
Supply Current	I_{SS}	$I_{OUT}=0A$	$V_{OUT}\leq 5.0V$	—	3	μA
			$V_{OUT}>5.0V$	—	5	μA
Standby Current	I_{STBY}	$CE = V_{SS}$	—	0.1	0.5	μA
Line Regulation	$\frac{\Delta V_{OUT}}{V_{OUT} \times \Delta V_{IN}}$	$I_{OUT}=10mA$ $V_{OUT}+1V \leq V_{IN} \leq 18V$	—	0.01	0.3	%/V
Load Regulation	ΔV_{OUT}	$V_{IN}=V_{OUT}+1V$, $1mA \leq I_{OUT} \leq 100mA$	—	10	—	mV
Temperature Coefficient	$\frac{\Delta V_{OUT}}{V_{OUT} \times \Delta T_A}$	$I_{OUT}=10mA$, $-40^\circ C < T_A < 125^\circ C$	—	50	—	ppm
Output Current Limit	I_{LIM}	$V_{OUT}=0.5 \times V_{OUT(Normal)}$, $V_{IN}=5V$	150	250	—	mA
Short Current	I_{SHORT}	$V_{OUT}=V_{SS}$	—	20	—	mA
Power Supply Rejection Ratio	PSRR	$I_{OUT}=50mA$	100Hz	—	75	dB
			1kHz	—	80	
			10kHz	—	60	
			100kHz	—	45	
Output Noise Voltage	V_{ON}	$BW=10Hz$ to $100kHz$	—	$27 \times V_{OUT}$	—	μV_{RMS}
Thermal Shutdown Temperature	T_{SD}	—	—	170	—	$^\circ C$
Thermal Shutdown Hysteresis	ΔT_{SD}	—	—	20	—	$^\circ C$
CE "High" Voltage	$V_{CE"H"}$		1.5	—	V_{IN}	V
CE "Low" Voltage	$V_{CE"L"}$		—	—	0.3	V

■ TYPICAL APPLICATION CIRCUIT



External Components List

Symbol	Description
C_{IN}	1.0 μ F or more
C_{OUT}	1.0 μ F or more, 10 μ F is recommended

■ APPLICATION INFORMATION

■ Selection of Input/ Output Capacitors

Phase compensation is provided to secure operation even when the load current is varied. For this purpose, use a 1.0 μ F or more output capacitor (C_{OUT}) with good frequency characteristics and proper ESR (Equivalent Series Resistance). Connect a 1.0 μ F or more input capacitor (C_{IN}) between the V_{IN} pin and the V_{SS} pin as close as possible to the pins. The value of the output overshoot or undershoot transient response varies depending on the value of the output capacitor.

When selecting the output capacitor, perform sufficient evaluation, including evaluation of temperature characteristics, on the actual device.

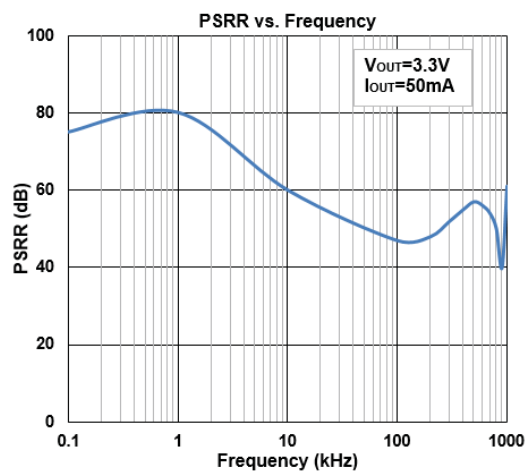
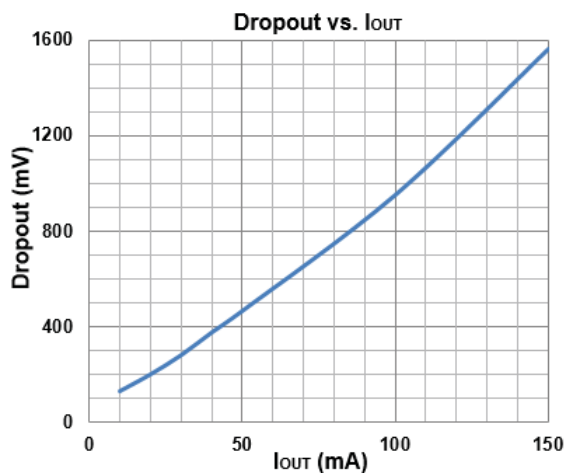
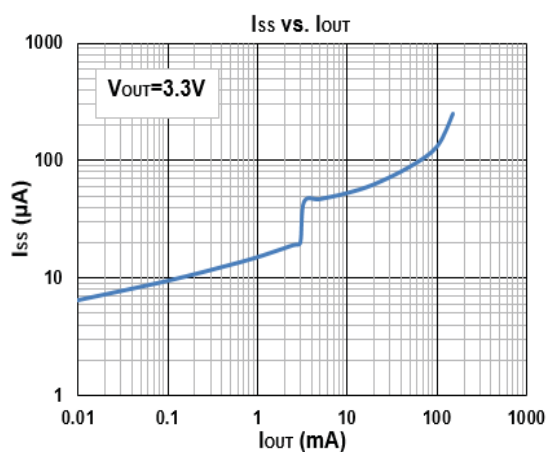
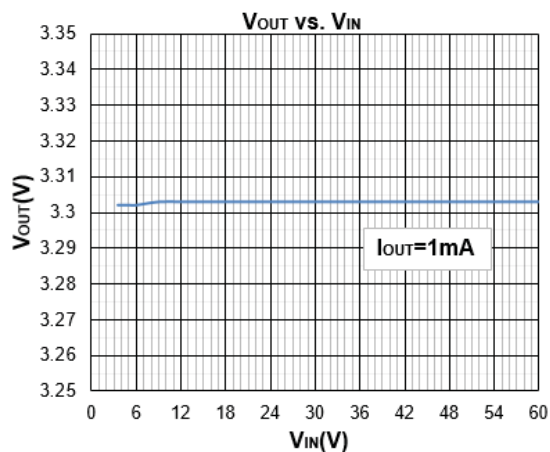
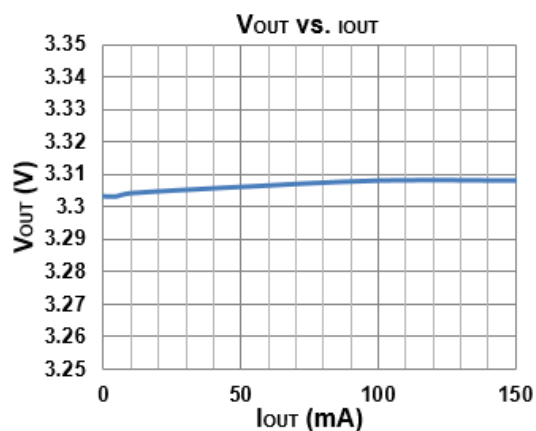
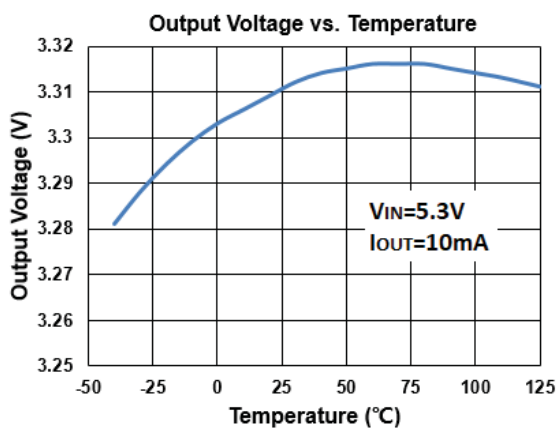
In the design of portable devices the ceramic capacitors are often chosen because of their small size, low equivalent series resistance (ESR) and high RMS current capability. Also, designers have been looking to ceramic capacitors due to shortages of tantalum capacitors.

Unfortunately, using ceramic capacitors for input filtering can cause problems. Applying a voltage step to a ceramic capacitor causes a large current surge that stores energy in the inductances of the power leads. A large voltage spike is created when the stored energy is transferred from these inductances into the ceramic capacitor. These voltage spikes can easily be twice the amplitude of the input voltage step.

Many types of capacitors can be used for input bypassing, however, caution must be exercised when using multilayer ceramic capacitors (MLCC). Because of the self-resonant and high Q characteristics of some types of ceramic capacitors, high voltage transients can be generated under some start-up conditions, such as connecting the LDO input to a live power source. Adding a 3 Ω resistor in series with an X5R ceramic capacitor will minimize start-up voltage transients.

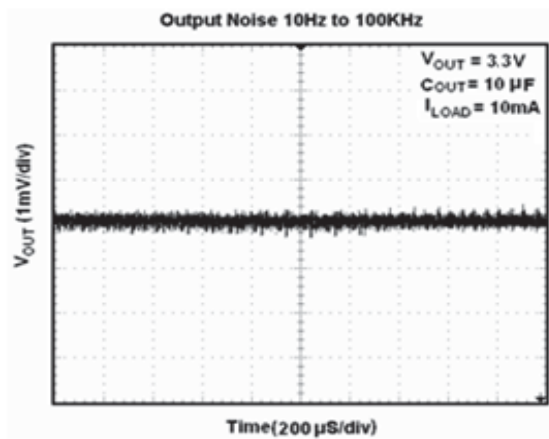
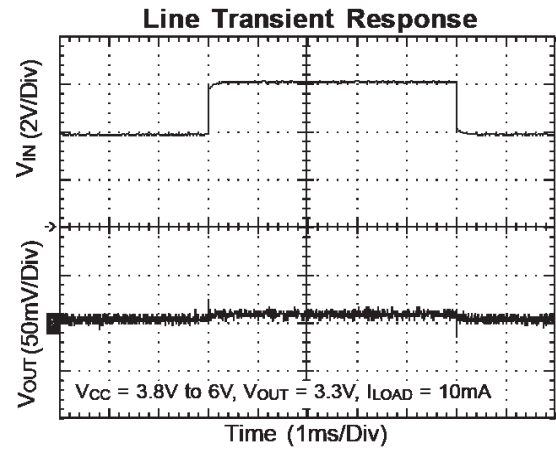
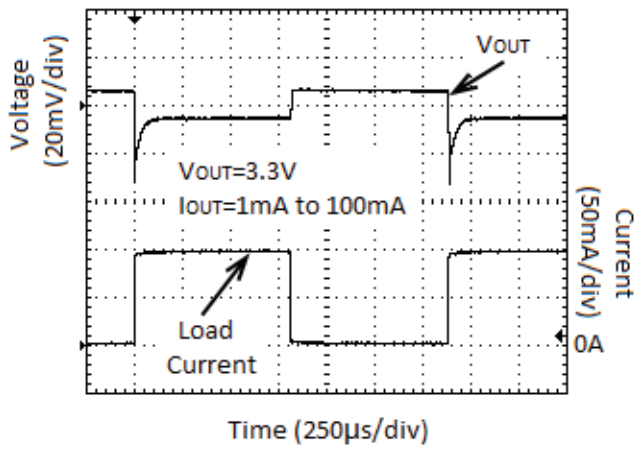
■ TYPICAL PERFORMANCE CHARACTERISTICS

($V_{CE}=V_{IN}=V_{OUT}+2V$, $C_{IN}=1\mu F$, $C_{OUT}=10\mu F$, $T_A=25^\circ C$, unless otherwise specified)



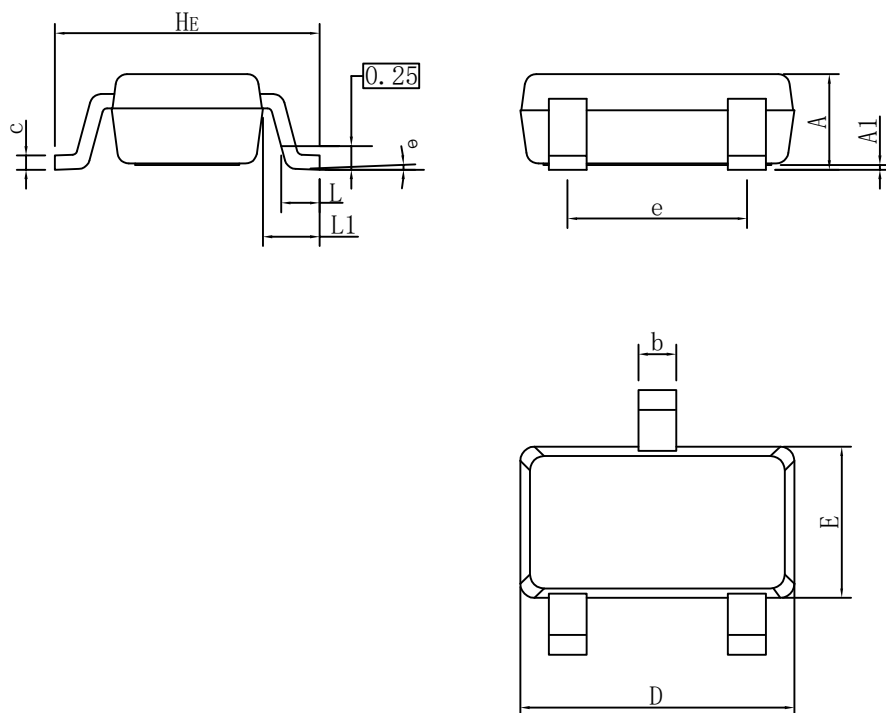
■ TYPICAL PERFORMANCE CHARACTERISTICS

($V_{CE}=V_{IN}=V_{OUT}+2V$, $C_{IN}=1\mu F$, $C_{OUT}=10\mu F$, $T_A=25^\circ C$, unless otherwise specified)



■ PACKAGING INFORMATION

● SOT-23-3 PACKAGE OUTLINE DIMENSIONS

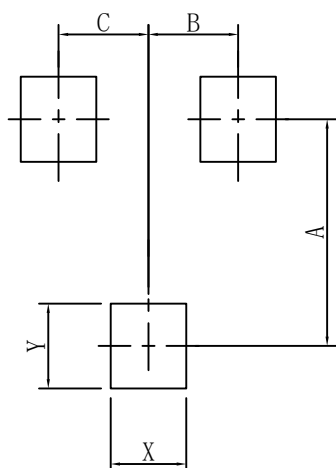


DIM	MIN	NOR	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
c	0.10	0.17	0.20
D	2.80	2.90	3.00
E	1.50	1.60	1.70
e	1.80	1.90	2.00
L	0.20	0.40	0.60
L1	0.60REF		
HE	2.60	2.80	3.00
θ	0°	-	10°
All Dimensions in mm			

GENERAL NOTES

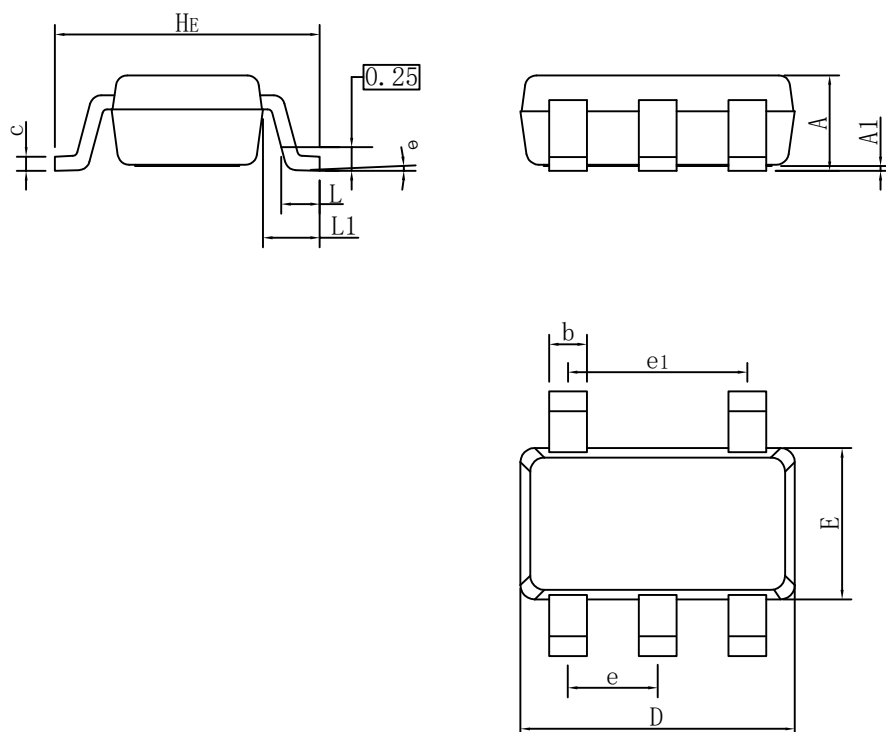
1. Top package surface finish $Ra0.4 \pm 0.2\mu m$
2. Bottom package surface finish $Ra0.7 \pm 0.2\mu m$
3. Side package surface finish $Ra0.4 \pm 0.2\mu m$

● SOLDERING FOOTPRINT



DIM	(mm)
X	0.80
Y	0.90
A	2.40
B	0.95
C	0.95

● SOT-23-5 PACKAGE OUTLINE DIMENSIONS

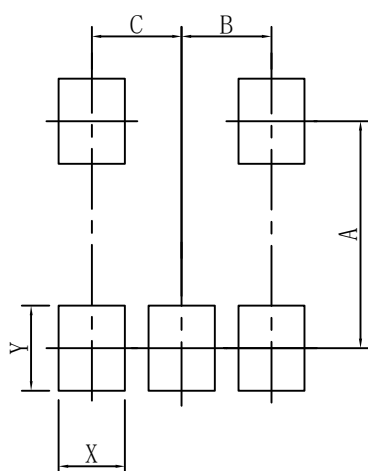


SOT25			
DIM	MIN	NOR	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
c	0.10	0.17	0.20
D	2.80	2.90	3.00
E	1.50	1.60	1.70
e	0.85	0.95	1.05
e1	1.80	1.90	2.00
L	0.20	0.40	0.60
L1	0.60REF		
HE	2.60	2.80	3.00
θ	0°	-	10°

GENERAL NOTES

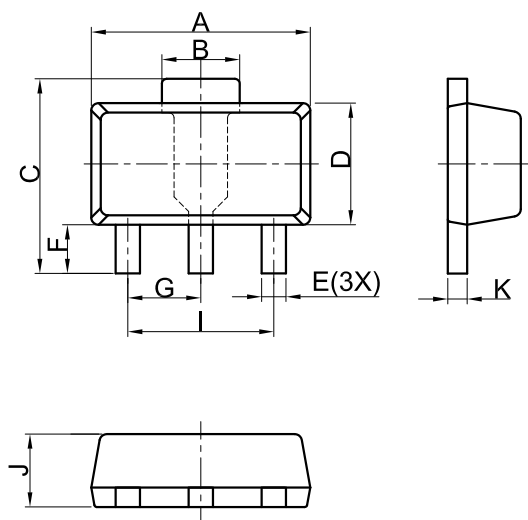
1. Top package surface finish $Ra0.4 \pm 0.2\mu m$
2. Bottom package surface finish $Ra0.7 \pm 0.2\mu m$
3. Side package surface finish $Ra0.4 \pm 0.2\mu m$

● SOLDERING FOOTPRINT



SOT25	
DIM	(mm)
X	0.70
Y	0.90
A	2.40
B	0.95
C	0.95

● **SOT-89-3 PACKAGE OUTLINE DIMENSIONS**

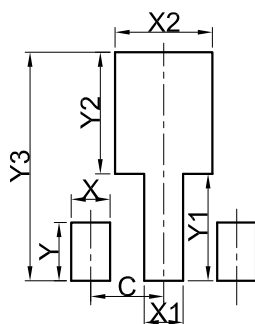


SOT89			
DIM	MIN	NOR	MAX
A	4.30	4.50	4.70
B	1.40	1.60	1.80
C	3.90	4.00	4.25
D	2.30	2.50	2.70
E	0.40	0.50	0.58
F	0.90	1.00	1.20
G	1.50 BSC		
I	3.00 BSC		
J	1.40	1.50	1.60
K	0.34	0.40	0.50
All Dimensions in mm			

GENERAL NOTES

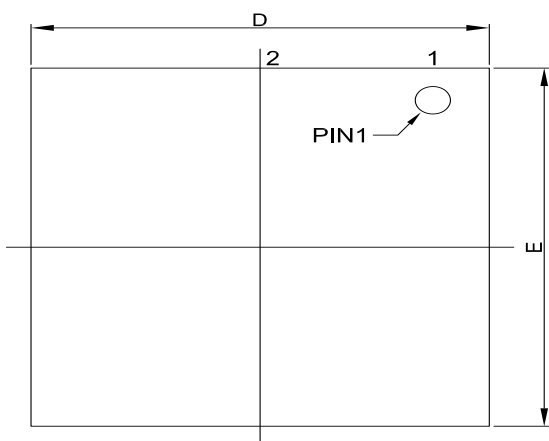
1. Top package surface finish $Ra0.4\pm0.2\mu m$
2. Bottom package surface finish $Ra0.7\pm0.2\mu m$
3. Side package surface finish $Ra0.4\pm0.2\mu m$
4. Protrusion or Gate Burrs shall not exceed 0.10mm per side.

● **SOLDERING FOOTPRINT**

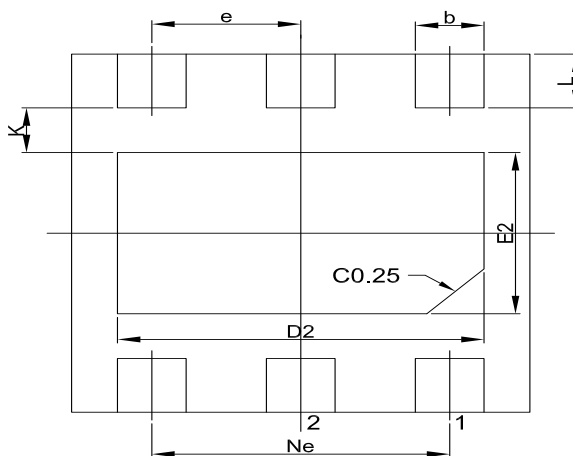


SOT89	
DIM	(mm)
X	0.80
Y	1.20
X1	0.80
Y1	2.20
X2	2.00
Y2	2.50
C	1.50
Y3	4.70

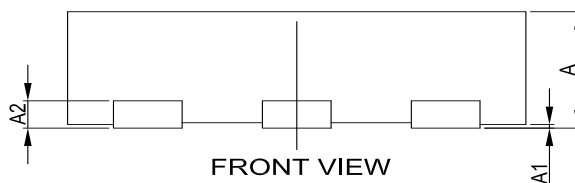
● DFN2020-6 PACKAGE OUTLINE DIMENSIONS



TOP VIEW



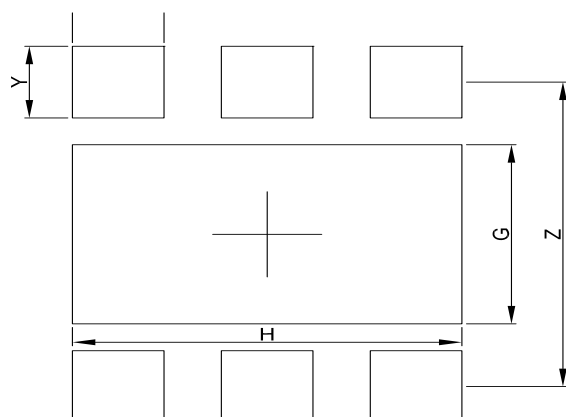
BOTTOM VIEW



FRONT VIEW

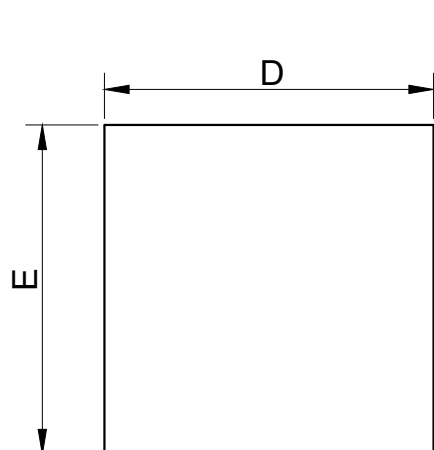
DIM	MILLIMETER		
	MIN	NOM	MAX
A	0.60	0.65	0.70
A ₁	---	0.02	0.05
A ₂	0.152 REF		
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D2	1.50	1.60	1.70
Ne	1.30 BSC		
e	0.65 BSC		
E	1.95	2.00	2.05
E2	0.85	0.90	0.95
L	0.25	0.30	0.35
K	0.20	0.25	0.30

● SOLDERING FOOTPRINT

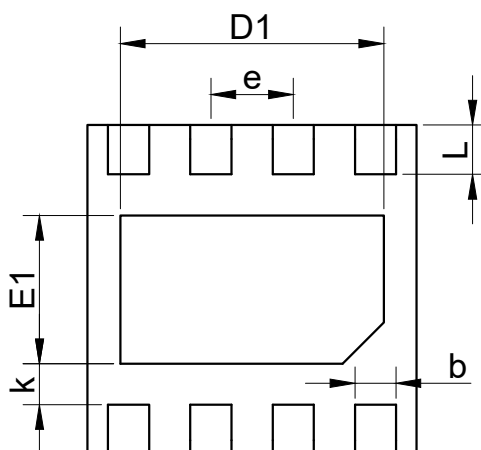


Dimensions	(mm)
G	1.00
H	1.70
J	0.65
X	0.40
Y	0.40
Z	1.70

● **DFN2020-8 PACKAGE OUTLINE DIMENSIONS**

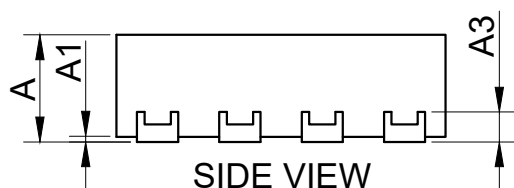


TOP VIEW



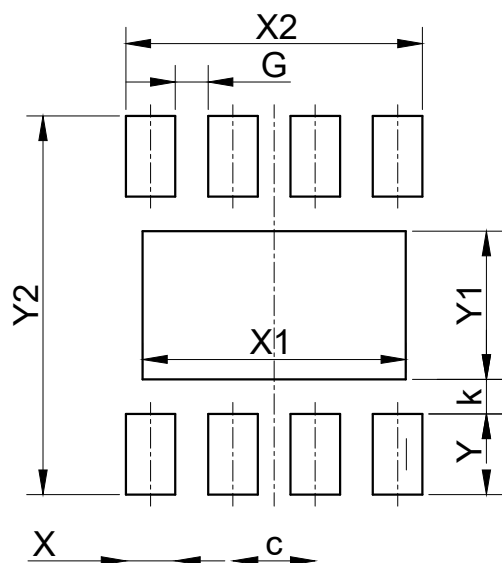
BOTTOM VIEW

DFN2020-8B(T0.65)			
DIM	MIN	NOR	MAX
A	0.60	0.65	0.70
A1	0.01	0.03	0.05
b	0.20	0.25	0.30
D	1.95	2.00	2.05
E	1.95	2.00	2.05
e	0.50TYP.		
L	0.25	0.30	0.35
D1	1.55	1.60	1.65
E1	0.85	0.90	0.95
A3	0.152REF.		
All Dimensions in mm			



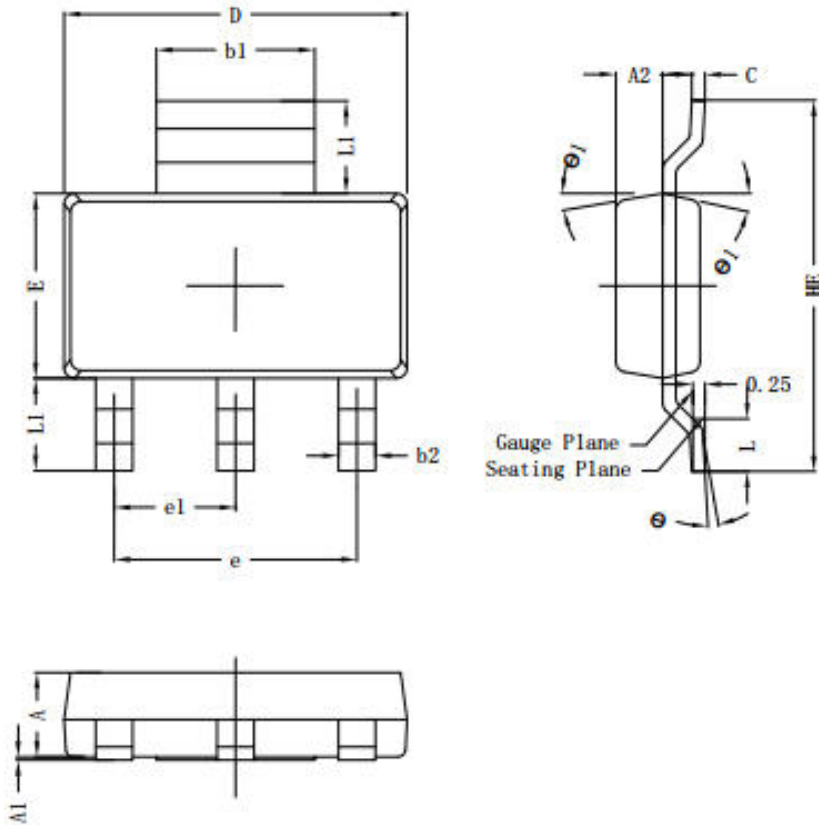
SIDE VIEW

● **SOLDERING FOOTPRINT**



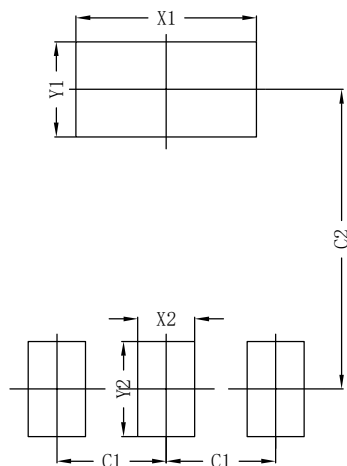
DFN2020-8B(T0.65)	
DIM	(mm)
c	0.50
G	0.20
k	0.21
X	0.30
X1	1.60
X2	1.80
Y	0.49
Y1	0.90
Y2	2.30

● SOT223 PACKAGE OUTLINE DIMENSIONS



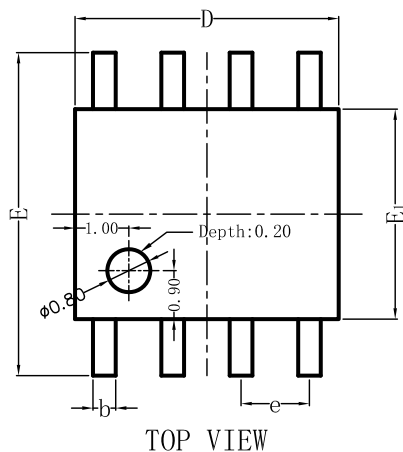
SOT223			
DIM	MIN	NOR	MAX
A	1.50	1.60	1.70
A1	0.00	0.05	0.10
A2	0.80	0.90	1.00
b1	2.90	3.02	3.10
b2	0.60	0.72	0.80
c	0.20	0.27	0.30
D	6.30	6.50	6.70
E	3.30	3.50	3.70
e	4.60BSC		
e1	2.30BSC		
HE	6.80	7.00	7.20
L	0.80	1.00	1.20
L1	1.75(REF)		
θ	0°-8°		
θ 1	8°	10°	12°
All Dimensions in mm			

Suggested Pad layout

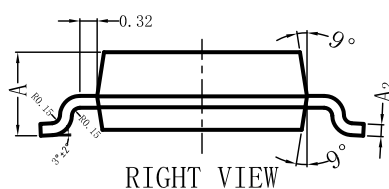
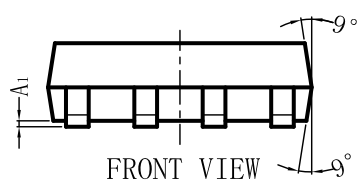


SOT223	
DIM	(mm)
X1	3.80
Y1	2.00
X2	1.20
Y2	2.00
C1	2.30
C2	6.30

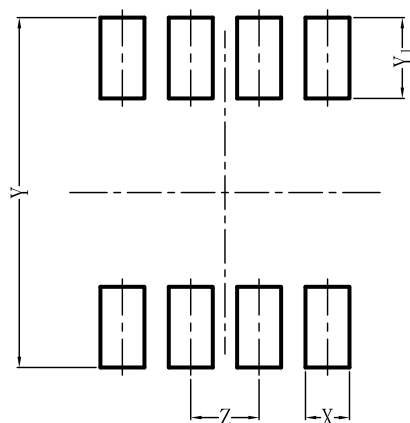
● SOP-8 PACKAGE OUTLINE DIMENSIONS



SOP8 (Unit:mm)			
Dim	Min	Typ	Max
A	1.35	1.55	1.75
A1	0.06	—	0.16
A2	0.19	0.22	0.25
b	0.33	0.42	0.51
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27BSC		



● SOLDERING FOOTPRINT



Dimensions	(mm)
X	0.820
Y	6.500
Y1	1.500
Z	1.270

■ ORDER INFORMATION APPENDIX

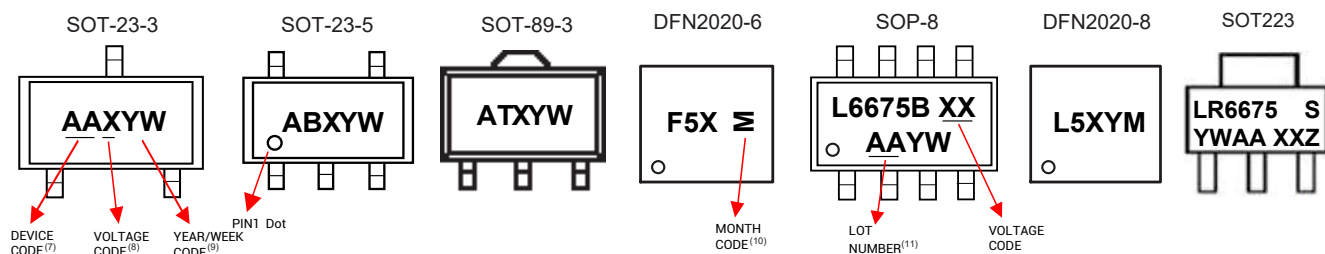
Device ⁽⁴⁾	Output Voltage ⁽⁵⁾	Package	Marking ⁽⁶⁾	Shipping
LR6675AxxM	1.2V~12V	SOT-23-3	AAX	3K/Reel
LR6675AxxMC	1.2V~12V	SOT-23-3	ACX	3K/Reel
LR6675AxxMY	1.2V~12V	SOT-23-3	AYX	3K/Reel
LR6675BxxM	1.2V~12V	SOT-23-5	ABX	3K/Reel
LR6675BxxMK	1.2V~12V	SOT-23-5	AKX	3K/Reel
LR6675AxxP	1.2V~12V	SOT-89-3	ADX	5K/Reel
LR6675AxxPL	1.2V~12V	SOT-89-3	ALX	5K/Reel
LR6675AxxPT	1.2V~12V	SOT-89-3	ATX	5K/Reel
LR6675AxxP1	1.2V~12V	SOT-89-3	AZX	5K/Reel
LR6675AxxPT1	1.2V~12V	SOT-89-3	AWX	5K/Reel
LR6675BxxFT	1.2V~12V	DFN202-6	F5X	4K/Reel
LR6675BxxFL	1.2V~12V	DFN202-8	L5X	3K/Reel
LR6675AxxS	1.2V~12V	SOP-8	L6675S	4K/Reel
LR6675BxxX	1.2V~12V	SOP-8	L6675B	4K/Reel

(4) The "xx" in part number represents output voltage, eg "18" = 1.8V, "50" = 5.0V.

(5) Output voltage varies from 1.2V to 12.0V, 0.1V an interval.

(6) There are additional marking, which relates to the date code. For detailed information, please refer to MARKING INFORMATION APPENDIX below.

■ MARKING INFORMATION APPENDIX



(7) The first two letters in the Marking represent DEVICE CODE.

(8) The following letter "X" in the Marking changes along with the output voltage, as the chart shows below.

Voltage(V)	1.2	1.5	1.8	2.5	2.5 (1%)	2.7	2.8	3.0	3.0 (1%)	3.3	3.3 (1%)	3.6	4.0	5.0	5.0 (1%)	12.0
Symbol	E	F	G	H	X	I	J	K	B	L	Q	M	N	P	m	S

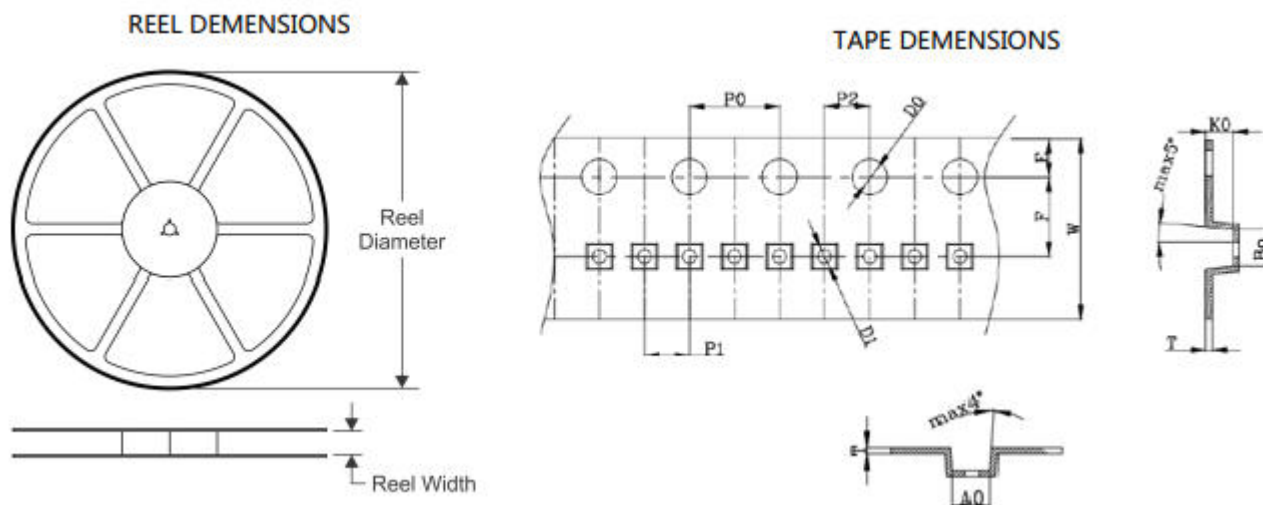
For SOP-8 packages, the VOLTAGE CODE is a two-digit or three-digit number changing along with the output voltage. For example, 18 = 1.8V, 33 = 3.3V, 50 = 5.0V, etc.

(9) The last two letters in the Marking represent YEAR/WEEK CODE or YEAR/MONTH CODE.

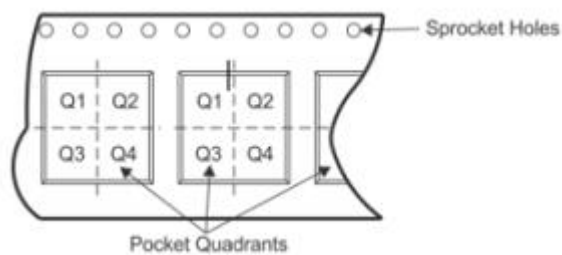
(10) For DFN2020-6 packages, the last letter in the Marking represents the MONTH CODE (Rotated 90° counter-clockwise).

(11) The LOT NUMBER is only used for internal production control of the factory.

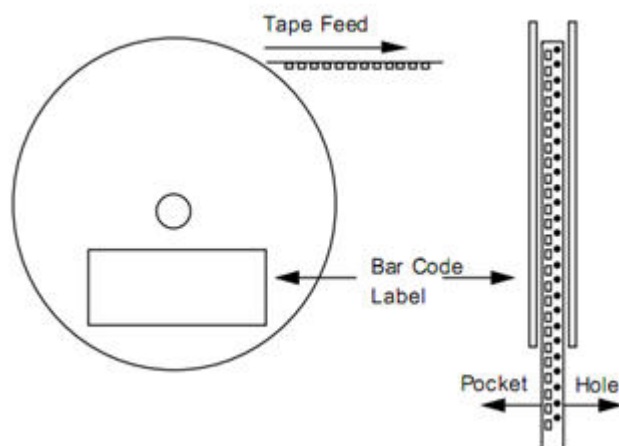
■ TAPE AND REEL INFORMATION



PIN ORIENTATION



ROLLING ORIENTATION



Device	Package	Reel Diameter (mm)	Reel width (mm)	P0 (mm)	P1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	W (mm)	PIN1
LR6675AxxM	SOT-23-3	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	8.0±0.1	NA
LR6675AxxMC	SOT-23-3	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	8.0±0.1	NA
LR6675AxxMY	SOT-23-3	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.1±0.1	3.28±0.1	1.32±0.1	8.0±0.1	NA
LR6675BxxM	SOT-23-5	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.25±0.05	3.15±0.05	1.5±0.05	8.0±0.1	Q3
LR6675BxxMK	SOT-23-5	178±1	9.6±1.2	4.00±0.1	4.00±0.1	3.25±0.05	3.15±0.05	1.5±0.05	8.0±0.1	Q3

■ REVISION HISTORY

Version	Description	Update by	Update Date
0.7	增加12V电压点对应的marking代码	Chen S	2023-02-23
0.8	增加LR6675BxxMK产品型号以及对应marking	Chen S	2023-12-01
0.9	增加LR6675BxxFT/ LR6675BxxX/LR6675AxxS 产品型号以及对应marking	Chen S	2024-02-26
1.0	增加LR6675BxxFL产品型号以及对应marking	Chen S	2024-06-12
1.1	SOT89包装数量由1K/卷更新为5K/卷 . SOT223包装数量由1K/卷更新为4K/卷.	Chen S	2024-08-27

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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